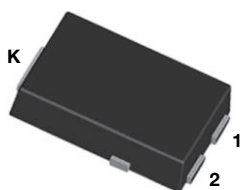
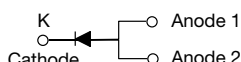


# SMD Photovoltaic Solar Cell Protection Schottky Rectifier

## eSMP® Series



**SMPC (TO-277A)**



## FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Guardring for overvoltage protection
- Low forward voltage drop, low power losses
- High efficiency
- Low thermal resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

## MECHANICAL DATA

**Case:** SMPC (TO-277A)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test

## LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	15 A
$V_{RRM}$	30 V
$I_{FSM}$	280 A
$E_{AS}$	20 mJ
$V_F$ at $I_F = 15$ A	0.42 V
$T_J$ max.	150 °C
Package	SMPC (TO-277A)
Circuit configuration	Single

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	SS15P3S	UNIT
Device marking code		153S	
Maximum repetitive peak reverse voltage	$V_{RRM}$	30	V
Maximum DC forward current (fig. 1)	$I_F$	15 <sup>(1)</sup>	A
		4.5 <sup>(2)</sup>	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	280	A
Non-repetitive avalanche energy at $I_{AS} = 2.0$ A, $T_J = 25$ °C	$E_{AS}$	20	mJ
Operating junction and storage temperature range	$T_{OP}, T_{STG}$	-55 to +150	°C
Junction temperature in DC forward current without reverse bias, $t \leq 1$ h <sup>(3)</sup>	$T_J$	$\leq 200$	°C

## Notes

<sup>(1)</sup> Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink

<sup>(2)</sup> Free air, mounted on recommended copper pad area

<sup>(3)</sup> Meets the requirements of IEC 61215 Ed. 2 bypass diode thermal test

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 7.5\text{ A}$	$V_F^{(1)}$	0.43	-	V
	$I_F = 15\text{ A}$		0.50	0.57	
	$I_F = 7.5\text{ A}$		0.32	-	
	$I_F = 15\text{ A}$		0.42	0.49	
Reverse current	$V_R = 30\text{ V}$	$T_A = 25\text{ }^{\circ}\text{C}$	150	1000	$\mu\text{A}$
		$T_A = 125\text{ }^{\circ}\text{C}$	59	120	mA
Typical junction capacitance	4.0 V, 1 MHz	$C_J$	930	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 40\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	VALUE	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)}$	100	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(2)}$	3	

**Notes**(1) Free air, mounted on recommended copper pad area. Thermal resistance  $R_{\theta JA}$  - junction to ambient.(2) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance  $R_{\theta JM}$  - junction to mount.**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SS15P3S-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel
SS15P3S-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel

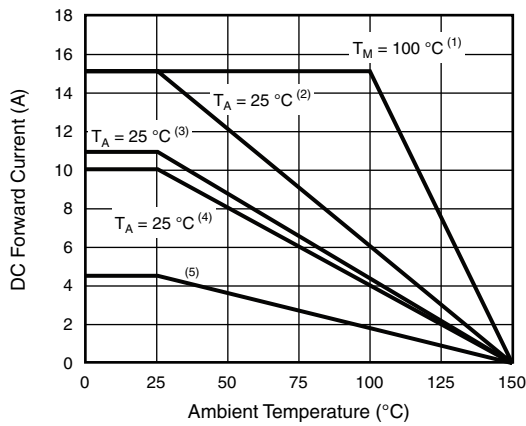
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Current Derating Curve

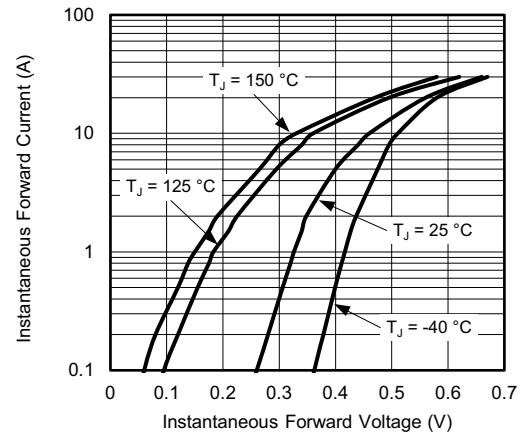


Fig. 3 - Typical Instantaneous Forward Characteristics

**Notes**

- (1) Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink,  $T_M$  measured at the terminal of cathode band
- (2) Mounted on 30 mm x 30 mm Al PCB ( $R_{\theta JA} = 20\text{ }^{\circ}\text{C/W}$ )
- (3) Mounted on 30 mm x 30 mm x 2 copper pad areas FR4 PCB ( $R_{\theta JA} = 30\text{ }^{\circ}\text{C/W}$ )
- (4) Mounted on 25 mm x 25 mm x 2 copper pad areas FR4 PCB ( $R_{\theta JA} = 30\text{ }^{\circ}\text{C/W}$ )
- (5) Free air, mounted on recommended copper pad area ( $R_{\theta JA} = 100\text{ }^{\circ}\text{C/W}$ )

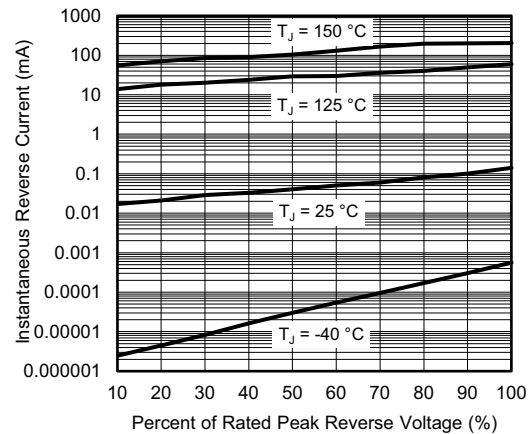


Fig. 4 - Typical Reverse Leakage Characteristics

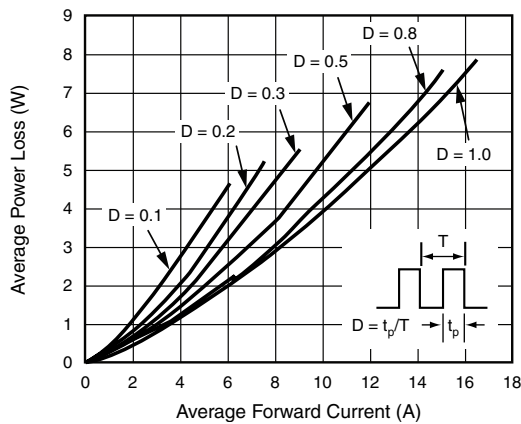


Fig. 2 - Forward Power Loss Characteristics

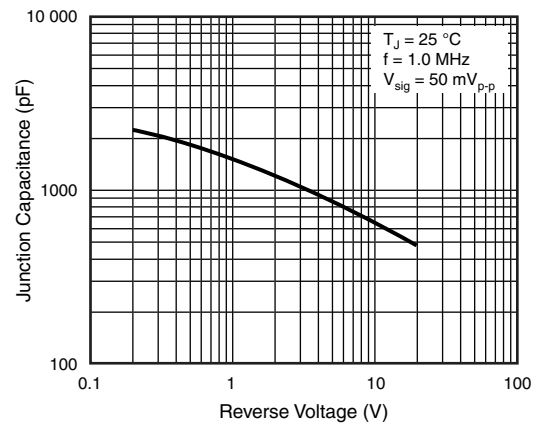
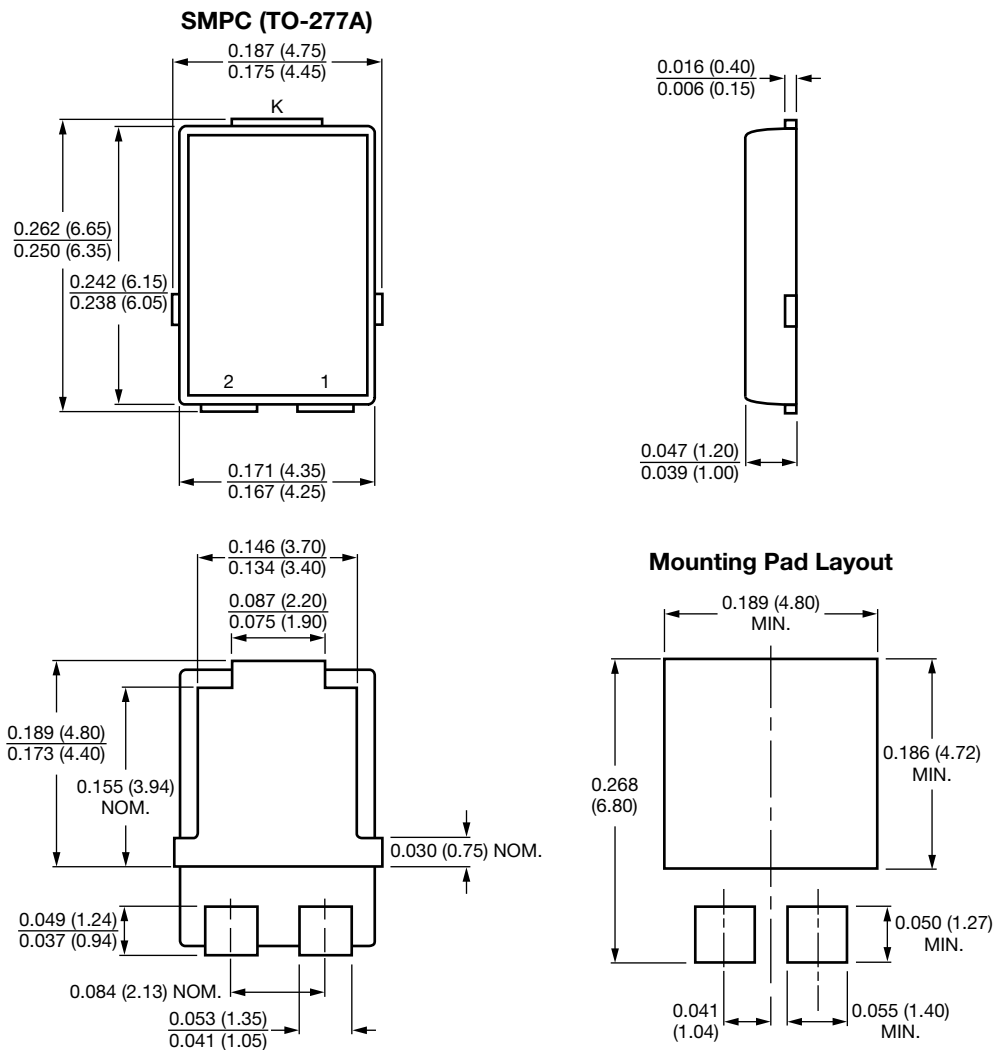


Fig. 5 - Typical Junction Capacitance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)




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